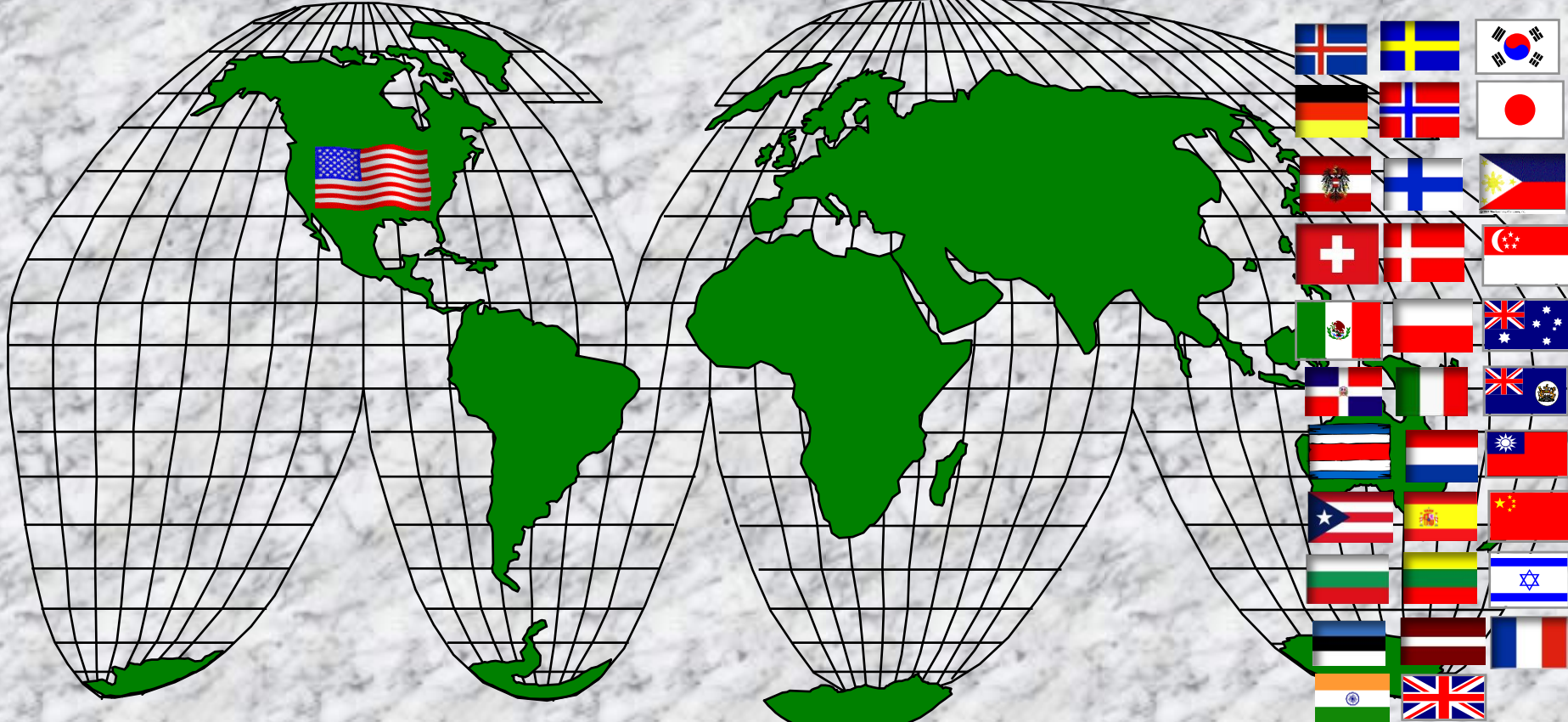





# MICROCOAT TECHNOLOGIES



Prosper, Texas, Cheshire, CT, Research Triangle Park, NC USA

<http://www.m-coat.com>





**MCT 34T71ND-2  
MSL1 Circuit Sealing  
Adhesive**

**Overview of a single-component,  
toughened microelectronic grade package sealant**



The background features a close-up of a circular silicon wafer with a grid of colorful microchips. A single, larger, gold-colored microchip is positioned in the foreground, slightly overlapping the wafer. The entire scene is set against a light blue gradient background with a large, semi-transparent white diamond shape centered behind the text.

Application Areas: Military,  
Medical, Optoelectronics,  
Automotive Sensors, LCP  
Packages

The background of the slide features a close-up, slightly blurred image of a microchip or integrated circuit. The chip's surface is covered in a complex grid of tiny, colorful components, likely representing different functional blocks or memory cells. A large, semi-transparent yellow diamond shape is overlaid on the center of the image, pointing downwards. The text is positioned to the left of the diamond.

**Feature 1:** Single-component system

No need for mixing before use

**Feature 2:** Room temperature storable for

30 days

***No viscosity changes over time***



A close-up photograph of a microchip with a grid of colorful pixels. A single gold die is placed on top of the chip, slightly offset from the center. The background is a soft, out-of-focus blue and white gradient.

**Feature 3:** Versatile cure schedules  
available

**Feature 4:** High shear and peel strength  
Suitable for bonding similar and  
dissimilar substrates

The background of the slide features a close-up, slightly blurred image of a microchip or integrated circuit. The chip's surface is covered in a dense grid of small, colorful components, likely solder balls or micro-bumps, in shades of blue, green, and purple. A large, semi-transparent yellow arrow with a black outline points diagonally downwards from the top-left towards the bottom-right, overlaid on the chip image. The overall background has a light blue gradient.

## **Feature 5:** Wide temperature range

Can withstand temperatures from  $-65^{\circ}\text{C}$  to  $340^{\circ}\text{C}$

Color changes slightly to amber above  $300^{\circ}\text{C}$

## **Feature 6:** Low moisture absorption

H<sub>2</sub>O absorption is less than 0.04%, similar to LCP

Passes MSL1 (Moisture Sensitivity Level 1)

requirements





**Feature 7:** Excellent performance in environmental testing

Passes 3500 hours at 85°C/85% RH (Relative Humidity)

Passes Gross Leak - Seal Integrity test

**Additional Features:**

Good electrical insulating properties and chemical resistance

Superior resistance to thermal shock, impact, and stress cracking fatigue

Meets NASA low outgassing specifications

RoHS compliant: Does not contain hazardous substances

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